

SOT1526-4

LFBGA529, plastic, low profile fine-pitch ball grid array; 529 balls; 0.8 mm pitch; 19 mm x 19 mm x 1.25 mm body

7 August 2018

Package information

1 Package summary

| | |
|--------------------------------|--|
| Terminal position code | B (bottom) |
| Package type descriptive code | LFBGA529 |
| Package style descriptive code | LFBGA (low profile fine-pitch ball grid array) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-275 PPAC-1 |
| Mounting method type | S (surface mount) |
| Issue date | 13-07-2018 |
| Manufacturer package code | 98ASA00744D |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|------|-----|------|
| package length | - | 19 | - | mm |
| package width | - | 19 | - | mm |
| package height | - | 1.25 | - | mm |
| nominal pitch | - | 0.8 | - | mm |
| actual quantity of termination | - | 529 | - | |



LFBGA529, plastic, low profile fine-pitch ball grid array; 529 balls; 0.8 mm pitch; 19 mm x 19 mm x 1.25 mm body

2 Package outline

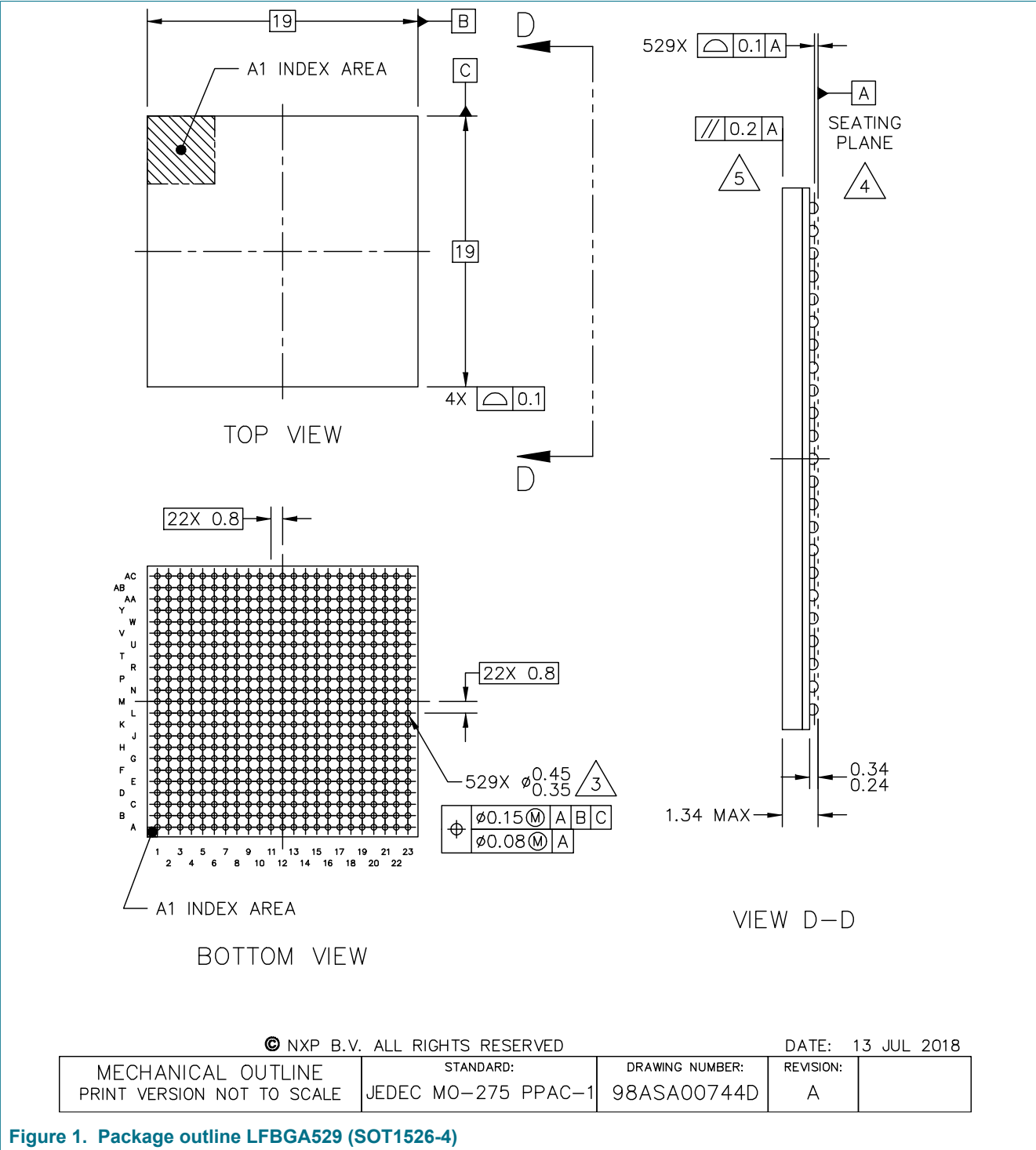


Figure 1. Package outline LFBGA529 (SOT1526-4)

LFBGA529, plastic, low profile fine-pitch ball grid array; 529 balls; 0.8 mm pitch; 19 mm x 19 mm x 1.25 mm body

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
- 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

| | | | | |
|--|----------------------------------|--------------------------------|-------------------|--|
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| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE | STANDARD: JEDEC MO–275 PPAC–1 | DRAWING NUMBER: 98ASA00744D | REVISION: A | |

Figure 2. Package outline noteLFBGA529 (SOT1526-4)

3 Legal information

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